

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	TLE4998C8	**Issued**	1. August 2018
MA#	MA002627786		
Package	PG-TDSO-8-1	**Weight***	66.82 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.926	2.88	2.88	28818	28818
leadframe	non noble metal	zinc	7440-66-6	0.062	0.09		926	
	non noble metal	tin	7440-31-5	0.077	0.12		1158	
	non noble metal	chromium	7440-47-3	0.093	0.14		1389	
	non noble metal	copper	7440-50-8	30.717	45.97	46.32	459671	463144
wire	noble metal	gold	7440-57-5	0.058	0.09	0.09	874	874
encapsulation	organic material	carbon black	1333-86-4	0.065	0.10		968	
	plastics	epoxy resin	-	3.494	5.23		52292	
	inorganic material	silicondioxide	60676-86-0	28.796	43.09	48.42	430927	484187
leadfinish	non noble metal	tin	7440-31-5	0.497	0.74	0.74	7441	7441
plating	noble metal	silver	7440-22-4	0.793	1.19	1.19	11868	11868
glue	plastics	epoxy resin	-	0.061	0.09		917	
	plastics	acrylic resin	-	0.061	0.09		917	
	inorganic material	silicondioxide	60676-86-0	0.123	0.18	0.36	1834	3668
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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